

04-19-2002

FORM PTO-1596
1-31-92

DOCKET NO.: 4459-089

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

To the Honorable Commissioner of Pa

102061178

See attached original documents or copy thereto:

1. Name of conveying party(ies):

1) Chih Ming CHUNG

04/15/02

Additional name(s) of conveying party(ies) attached?

2. Name and address of receiving party(ies):

Name: **ADVANCED SEMICONDUCTOR
ENGINEERING, INC.**

Internal Address:

Street Address: **No. 26, Chin 3rd Road, Nantze Export
Processing Zone**City: **Kaoshiung**State or Area: **Taiwan**

Zip/Postal Code:

Country: **R.O. C.**1036 U.S. PTO
10/121510

04/15/02

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ OtherExecution Date: **March 18, 2002**

Additional name(s) & address(es) attached?

4. Application number(s) or patent number(s):

If the document is being filed together with a new application, the execution date of the application is: **March 18, 2002**

A. Patent Application No(s).

B. Patent No(s).

Additional numbers attached?

5. Name and address of party to whom correspondence
concerning document should be mailed:

Name:

LOWE HAUPTMAN GILMAN & BERNER (22429)

Internal Address:

Street Address: **1700 Diagonal Road, Suite 310**City: **Alexandria**State: **VA**ZIP: **22314**

6. Total number of applications and patents involved: one

7. Total fee (37 CFR 3.41)

\$40.00

☒ Credit Card payment form enclosed☐ Authorized to be charged to deposit account

8. Deposit account number: 07-1337

DO NOT USE THIS SPACE

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document*Benjamin J. Hauptman Reg. No. 29,310

Name and Registration No. of Person Signing

Signature

April 15, 2002

Date

Total number of pages comprising cover sheet: 1

CMB No. 0851-0011 (exp. 4/94)

04/16/2002 ANABI1 00000052 10121510

02 FC:581

40.00 DP

PATENT
REEL: 012794 FRAME: 0408

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

(1) Chih Ming CHUNG (4) _____
 (2) _____ (5) _____
 (3) _____ (6) _____

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Advanced Semiconductor Engineering, Inc.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR CHIP PACKAGE AND MANUFACTURING METHOD THEREOF

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on March 18, 2002,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside our signatures:

INVENTORS

DATE SIGNED

1) Signature: Chih Ming CHUNG Chih Ming Chung
 Name: _____

March 18, 2002 _____

2) Signature _____
 Name: _____

3) Signature _____
 Name: _____

4) Signature _____
 Name: _____

5) Signature _____
 Name: _____

6) Signature _____
 Name: _____